# Deep Learning Applied to Image Processing

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Deadline for manuscript submissions:
**closed (20 March 2022)**

## Message from the Guest Editors

The purpose of this Special Issue is to broadly engage the communities of DL and IP together in order to provide a forum for the researchers and practitioners related to this rapidly developing field and share their novel and original research regarding the topic of Deep Learning applied to Image Processing. Additionally, survey papers addressing relevant topics of DL&IP are also welcome. Topics of interest include but are not limited to:

- Medical imaging;

- Image restoration;

- Deep adversarial learning for IP;

- Image registration;

- Image segmentation;

- Nature-inspired and metaheuristic algorithms for DL&IP;

- Theoretical analysis of DL models for DL&IP.

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Special Issue

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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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